

L Number	Hits	Search Text	DB	Time stamp
1	90325	surfactant	USPAT; US-PPGPUB	2002/11/14 12:22
2	69317	stabilizer	USPAT; US-PPGPUB	2002/11/14 12:22
3	21306	electroplating	USPAT; US-PPGPUB	2002/11/14 12:22
4	857105	solution	USPAT; US-PPGPUB	2002/11/14 12:22
5	204434	bath	USPAT; US-PPGPUB	2002/11/14 12:22
6	280456	copper	USPAT; US-PPGPUB	2002/11/14 12:31
7	25987	trench	USPAT; US-PPGPUB	2002/11/14 12:31
8	309873	recess	USPAT; US-PPGPUB	2002/11/14 12:31
9	1055009	via	USPAT; US-PPGPUB	2002/11/14 12:31
10	508547	hole	USPAT; US-PPGPUB	2002/11/14 12:31
11	1542550	trench recess via hole	USPAT; US-PPGPUB	2002/11/14 12:31
12	136610	(trench recess via hole) and copper	USPAT; US-PPGPUB	2002/11/14 12:31
13	5559	electroplating same solution	USPAT; US-PPGPUB	2002/11/14 12:31
14	4814	electroplating same bath	USPAT; US-PPGPUB	2002/11/14 12:32
15	2666	((trench recess via hole) and copper) and ((electroplating same solution) (electroplating same bath))	USPAT; US-PPGPUB	2002/11/14 12:32
16	61	((trench recess via hole) and copper) and ((electroplating same solution) (electroplating same bath))) and surfactant and stabilizer	USPAT; US-PPGPUB	2002/11/14 12:32
17	1526	bipyridyl	USPAT; US-PPGPUB	2002/11/14 12:32
18	2	((trench recess via hole) and copper) and ((electroplating same solution) (electroplating same bath))) and surfactant and stabilizer) and bipyridyl	USPAT; US-PPGPUB	2002/11/14 12:33